External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00345	5.0	0.04991
	Lead alloy	Silver (Ag)	7440-22-4	0.00172	2.5	0.02495
	Lead alloy	Lead (Pb)	7439-92-1	0.06376	92.5	0.92324
			Subtotal	0.06893	100	0.9981
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.31768	100.0	4.6
			Subtotal	0.31768	100	4.6
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0232	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05801	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	57.92942	99.86	838.824
			Subtotal	58.01063	100	840
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.93369	100.0	28
			Subtotal	1.93369	100	28
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.37964	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.21543	16.0	90
	Filler	Silica fused	60676-86-0	29.13481	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11654	0.3	1.6875
			Subtotal	38.84642	100	562.5
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.82266	100.0	11.91217
			Subtotal	0.82266	100	11.91217
			Total	100.00001	100	1448.01027

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.